

TECH DAYS AGENDA



Cyber Resilience Act

TIME	COMPANY	TITLE	SPEAKER
9:00 – 9:10		WELCOME	Daniel Bogdanoff
9:10 – 9:40		Keynote Speech: Understanding the EU Cyber Resilience Act	Prof. Dr. Dennis-Kenji Kipker
9:45 – 10:15	EBV	The Cyber Resilience Act: New challenges and potentials in product-related cyber security	Daniel Bartz, EBV
10:20 – 11:25	Fraunhofer SIT Newtec TÜV IT Witekio EBV	Panel Discussion: Practical impacts of the CRA on product development	<ul style="list-style-type: none"> • Dr.-Ing. Steven Arzt • Stephan Strohmeier • Jacques Kruse Brandao • Julien Bernet • Daniel Bartz
		LUNCH	
13:00 – 13:25	Infineon	The Cyber Security Act (CRA): A paradigm shift in the EU market	Dr. Detlef Houdea
13:30 – 13:55	ST	Radio Equipment Directive & Cyber Resilience Act: Impact on your MCU related cyber security applications	Thierry Crespo, Souhir Mhira
14:00 – 14:25	NXP	NXP Offering to Comply with CRA	Jenirathese Nadar
14:30 – 14:55	Renesas	Solutions to Support CRA Requirements	Markus Vomfelde
15:00 – 15:20	Witekio	Dealing with CRA: From Initial Cybersecurity Risk Assessment to Maintenance in Secure Condition	Julien Bernet

September 3

Factory Communication

TIME	COMPANY	TITLE	SPEAKER
9:30 – 9:55	EBV	Market Trends & Technology Updates – Wired Communication	Karl Lehnhoff, Ulrich Schmidt
10:00 – 10:25	EBV	Market Trends & Technology Updates – Wireless Communication	Karl Lehnhoff, Christian Krieger
10:30 – 10:55	NXP	NXP Solutions	Christian Castel
11:00 – 11:25	Broadcom	Broadcom Solutions for the Factory Floor – Ethernet Communication	Steven Rossbach
11:30 – 11:55	Microchip	TSN Field Switches and Single Pair Ethernet for Industrial Platforms	Ian Saturley
		LUNCH	
13:00 – 13:25	Renesas	Renesas Solutions for Industrial Communication Components and Protocols	Arno Stock, David Renno
13:30 – 13:55	Toshiba	Understanding the Importance of TSN Ethernet in Industrial Networks	Goran Filimonovic
14:00 – 14:25	Infineon	Wireless Connectivity for Industrial Automation: The Power of Wi-Fi® and Bluetooth®	David Hoskins

September 12

TECH DAYS AGENDA



Control Level: PLCs & IPCs / HMI

September 17

TIME	COMPANY	TITLE	SPEAKER
9:30 – 9:55	EBV	Market Trends & Technology Updates: PLCs/IPCs	Karl Lehnhoff, Ulrich Schmidt
10:00 – 10:25	EBV Embedded Solutions	EBV Embedded Solutions	Volker Perske
10:30 – 10:55	Tria	How TRIA's Compute Technologies Reduce Time to Market and Increase Flexibility and Scalability	Bevan Braude
11:00 – 11:25	NXP	NXP - PLCs	Christian Castel
11:30 – 11:55	Nexperia	Nexperia - Protecting Critical Factory Automation Applications Against the Threat from ESD	Nelson Arrey
LUNCH			
13:00 – 13:25	EBV	Market Trends & Technology Updates: HMI	Karl Lehnhoff, Ulrich Schmidt
13:30 – 13:55	Renesas	Renesas - Introduction and Overview of the Renesas Solutions	Otto Roloff, Arno Stock
14:00 – 14:25	NXP	NXP - HMIs	Christian Castel
14:30 – 14:55	Tria	Customized HMI Made in Germany - the Perfect Fit with Tria	Bevan Braude
15:00 – 15:25	Infineon	Human Machine Interface: Industrial Panels with Infineon's CAPSENSE™	Elif Dogruer
15:30 – 15:55	Micron	Memory Considerations for the Factory Edge and Autonomous Machines	Wil Florentino
16:00 – 16:25	Kioxia	KIOXIA Flash Memory - For Reliable Control of your Factory Automation	Martin Juttner

Field Level: Actuators

September 24

TIME	COMPANY	TITLE	SPEAKER
9:30 – 9:55	EBV	Market Trends & Technology Update: Actuators	Karl Lehnhoff, Milan Ivkovic
10:00 – 10:25	Broadcom	Safety in Motor Drives	Tee Chun Keong
10:30 – 10:55	Nexperia	Low Voltage MOSFETs used in Factory Automation	Steven Waterhouse
11:00 – 11:25	onsemi	Autonomous Mobile Robot Concept Design	Alessandro Maggioni
11:30 – 11:55	Power Integrations	Power Conversion Efficiency for Electro-Mechanical Equipment	Dmitry Antonov
LUNCH			
13:00 – 13:25	Toshiba	How to Tackle the Challenges of Migrating an IGBT Based Drive Inverter to SiC MOSFETs	Matthias Ortmann
13:30 – 13:50	Infineon	Next-Generation Motor Control Solutions: Unlocking Efficiency and Performance with Infineon's Advanced Technologies	Kira Emmert

TECH DAYS AGENDA



Field Level: Sensors

September 25

TIME	COMPANY	TITLE	SPEAKER
9:30 – 9:55	EBV	Market Trends & Technology Updates: Machine Vision	Karl Lehnhoff, Ulrich Schmidt
10:00 – 10:25	onsemi	Selecting Imager Sensors for Machine Vision Applications	David Mills
10:30 – 10:55	ams OSRAM	Machine Vision	Clemens Müller
11:00 – 11:25	EBV	Market Trends & Technology Updates: General Sensors	Karl Lehnhoff, Uros Mali
11:30 – 11:55	Broadcom	Optical Sensing and Safety on the Factory Floor	Felix Donhöfner, Christian Liebhardt
LUNCH			
13:00 – 13:25	ST	Anomaly Detection and Predictive Maintenance Techniques in the Industrial Environment	Natale Testa
13:30 – 13:55	Renesas	Environmental Sensing for Industrial Applications	Florian Hirsch

Field Level: Analog & Digital I/O

September 26

TIME	COMPANY	TITLE	SPEAKER
9:30 – 9:55	EBV	Market Trends & Technology Updates: Analog & Digital I/Os	Karl Lehnhoff, Milan Ivkovic
10:00 – 10:25	NXP	Software Defined Factory with NXP's NAFE Family of Analog Front-Ends	Fabrizio Librizzi
10:30 – 10:55	SGMicro	Solutions for Typical Analog Input or Output Analog/Digital Modules	David Wallner
11:00 – 11:25	Broadcom	Overview of Digital Optocouplers and Solid-State Relays for Field Level I/O Applications	Vincent Ching
11:30 – 11:55	Nexperia	Galvanic Isolation for Factory Automation Applications	I.K. Anyiam
LUNCH			
13:00 – 13:25	ST	The Secrets Behind Designing Safety-Critical Automation Systems	Vojtech Elias
13:30 – 13:55	Infineon	Infineon's ISOFACE™ Comprehensive Solutions for Digital I/O	Kira Emmert